CHO-BOND® 1029

TWO COMPONENT FLEXIBLE ELECTRICALLY CONDUCTIVE SILICONE ADHESIVE

Customer Value Proposition:

CHO-BOND 1029 is a silver plated copper filled, two-component conductive silicone designed for applications where a flexible, strong, conductive electrical bond must be achieved. CHO-BOND 1029 greatly simplifies the problem of bonding conductive silicone EMI gaskets to metal substrates. It is formulated for relatively small bond lines (less than 0.010 inches (0.25mm)), and should not be used as an EMI caulk where bond lines are greater than 0.10 inches (0.25 mm). Low volatile organic compounds (VOCs) and minimal shrinkage upon curing make CHO-BOND 1029 a good choice for a variety of commercial and military applications. Curing of CHO-BOND 1029 can be achieved in as little as 30 minutes with heat to minimize equipment downtime and increase manufacturing throughput. CHO-BOND 1029 is supplied as a two component system, one part liquid and one part wet powder solid. For optimum mixing and material performance, the sand-like solid part should be added incrementally to the liquid part and mixed slowly over a 10 minute time period.

For best adhesion results, CHO-BOND 1029 should be used in conjunction with CHO-SHIELD 1085 primer. Typical applications include bonding, repair, and attachment of EMI gaskets, and sealing around EMI vents and windows.

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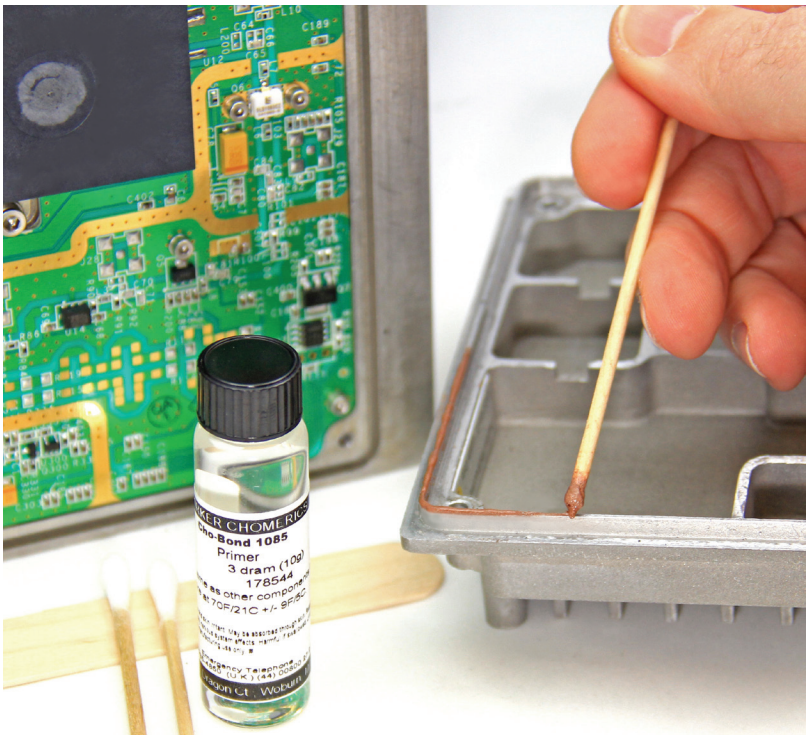

Features and Benefits:

- Two component
- Fast heat cure, increases throughput, minimizes equipment downtime.
- Silver plated copper filler
- Good conductivity 0.060 ohm-cm.
- Low VOCs
- Minimal shrinkage.
- Heat cure silicone
- Flexible, 120 minute working life, > 450 psi lap shear strength, 24 hr handling time at room temperature , wide range of application temperatures. 1 week for full cure.
- Non corrosive cure mechanism
- No corrosive by-products generated during curing to damage substrate.
- Thick paste
- Can be used on overhead or vertical surfaces.

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CHO-BOND 1029 - Product Information

Table 1 Typical Properties

CHO-BOND 1029			
Typical Properties	**Typical Values**	**Test Method**	
Polymer	Silicone	N/A	
Filler	Silver-Plated Copper	N/A	
Mix Ratio, A : B (by weight)	1.0 : 2.5	N/A	
Color	Brownish Red	N/A	(Q)
Consistency	Thick Paste	N/A	(Q)
Maximum DC Volume Resistivity	0.060 ohm-cm	CHO-95-40-5555*	(Q/C)
Minimum Lap Shear Strength**	450 psi (3103 kPa)	CHO-95-40-5300*	(Q/C)
Minimum Peel Strength**	6.0 lb./inch (1051 N/m)	CHO-95-40-5302*	(Q/C)
Specific Gravity	3.1	ASTM D792	(Q/C)
Hardness	80 Shore A	ASTM-D2240	(Q/C)
Continuous Use Temperature	- 55°C to 125°C (-67 °F to 257 °F)	N/A	(Q)
Elevated Temperature Cure Cycle	0.5 hour @ 121 °C (250 °F)	N/A	
Room Temperature Cure	1 week***	N/A	(Q)
Working Life	2.0 hours	N/A	(Q)
Shelf Life, unopened	6 months @ 25°C (77°F)	N/A	(Q)
Minimum thickness recommended	N/A	N/A	
Maximum thickness recommended	0.008 in (0.20 mm)	N/A	
Volatile Organic Content (VOC)	14 g/l	Calculated	
Theoretical Coverage Area at 0.010" Thick per Pound (454 grams)	900 in^2 (5806 cm^2)	N/A	
Theoretical Coverage - Length of an 1/8" Diameter Bead per Pound (454 grams)	60 feet (18.3 m)	N/A	

Note: N/A – Not Applicable, (Q/C) - Qualification and Conformance Test, (Q) - Qualification Test
* This test Method is available from Parker Chomerics.
** Minimum values listed are based on using the CHO-SHIELD 1085 primer that typically comes bundled with the CHO-BOND.
*** Cure is sufficient for handling in 24 hours. Full specification properties are developed after 1 week (168 hours) at room temperature.

Ordering Procedure

CHO-BOND 1029 is available in 3 oz. (85 g) and 1 lb. (454 g) kits. Each kit includes resin, hardener, primer and instructions.

Table 2 Ordering Information

Product	Weight (grams)	Packaging	Part Number	Primer Included
CHO-BOND 1029	85	Part A in an 4 oz. and Part B in a 4 oz. polypropylene kit	50-00-1029-0000	1085
	454	Part A in an 8 oz. and Part B in a 6 oz. polypropylene kit	50-01-1029-0000	1085

Please refer to Parker Chomerics Surface Preparation and CHO-BOND Application documents for information regarding the proper surface preparation, primer application (if required), and use of these compounds.

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